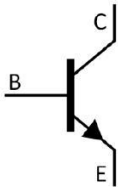


/ Descriptions

/ Features

/ Applications

/ Equivalent Circuit



/ Pinning



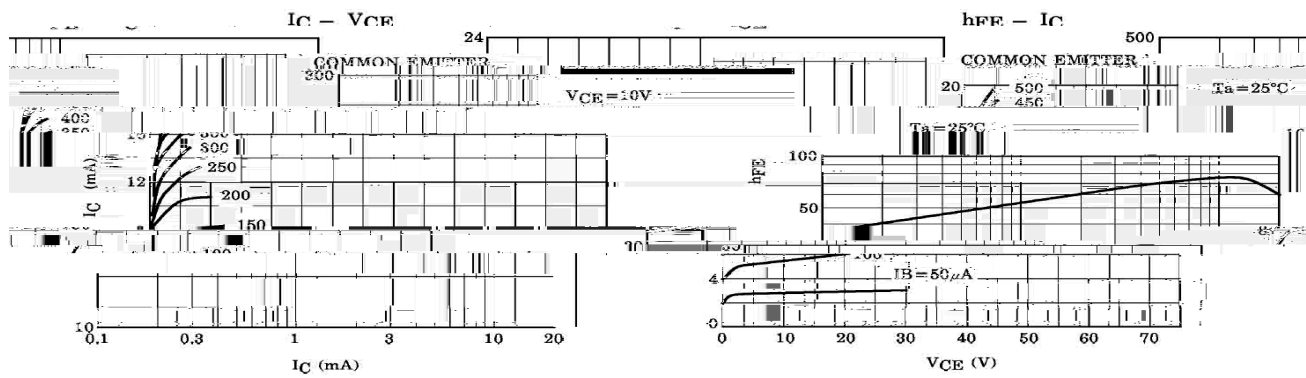
/ h_{FE} Classifications & Marking

	~	~	~	~	~

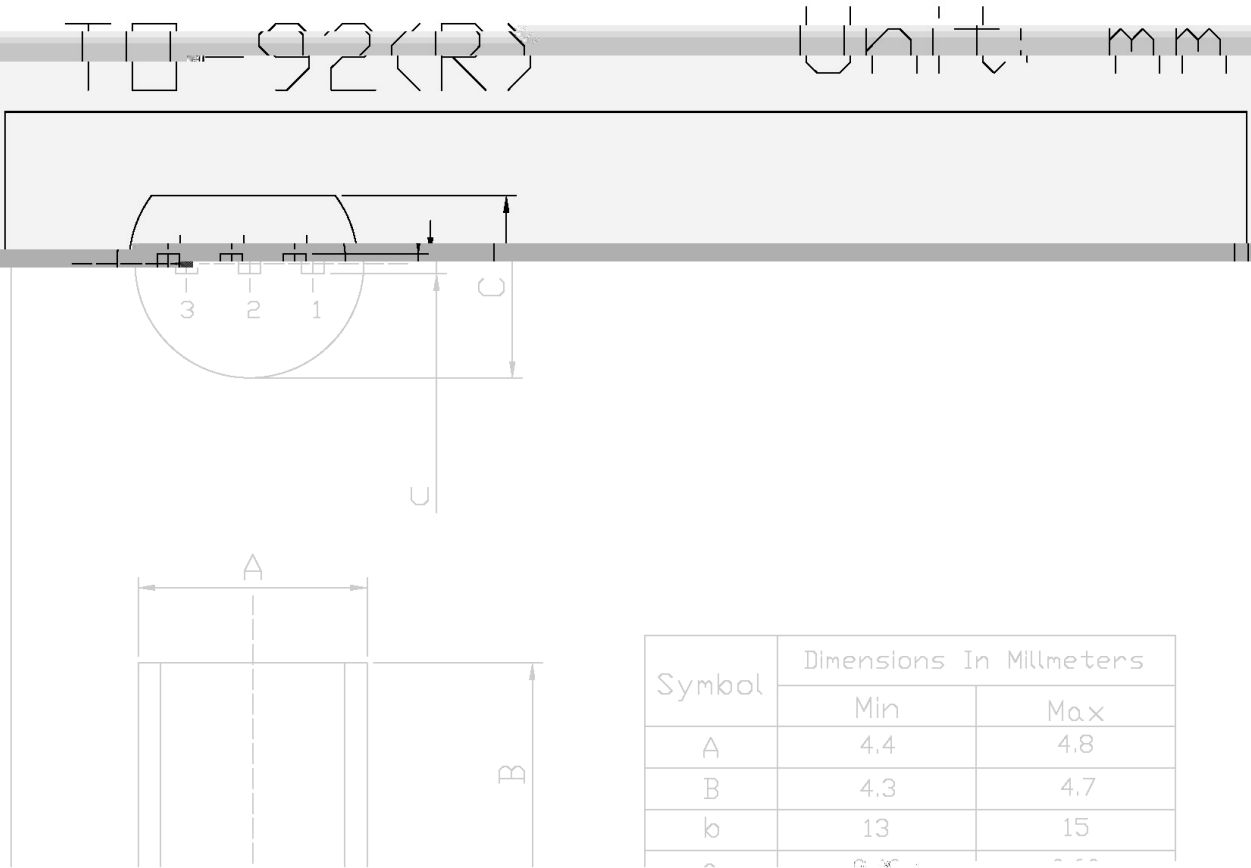
		~	

/ Electrical Characteristics(Ta=25)

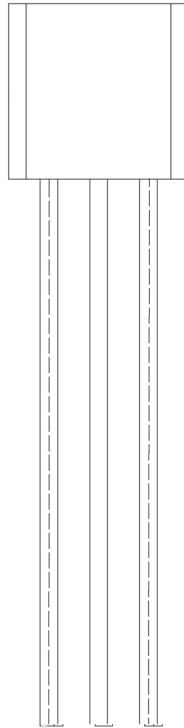
/ Electrical Characteristic Curve



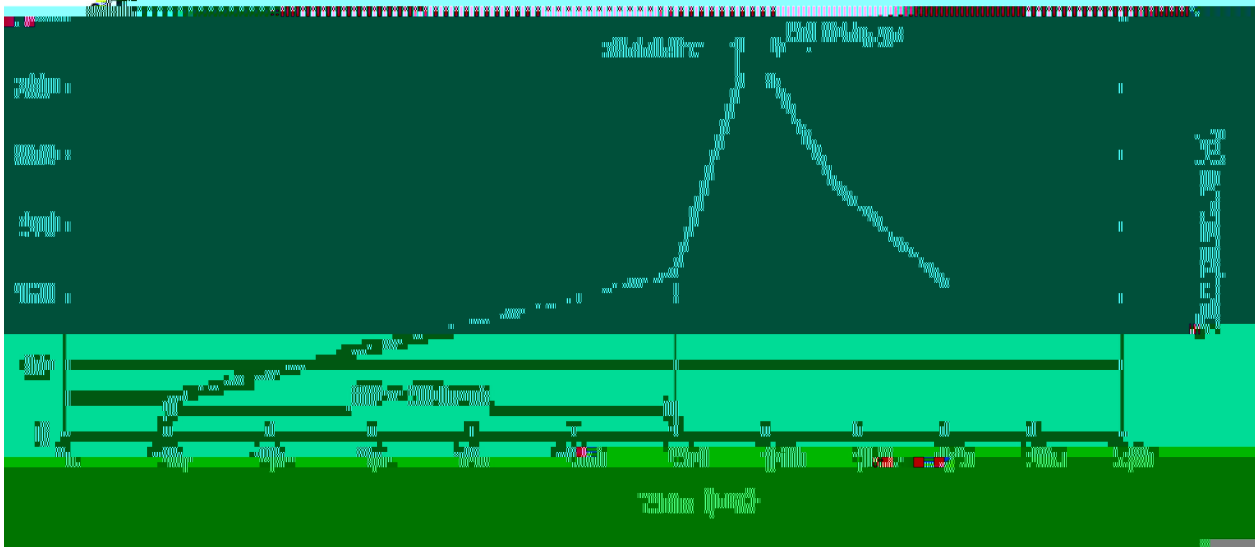
/ Package Dimensions



/ Marking Instructions



() / Temperature Profile for Dip Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	只 袋	袋 盒	只 盒	盒 箱	只 箱	袋	盒	箱

封装形式	包装数量					包装尺寸	
	只 纸带	纸带 盒	纸带层 盒	盒 箱	只 箱	盒	箱

小箱 ,
大箱